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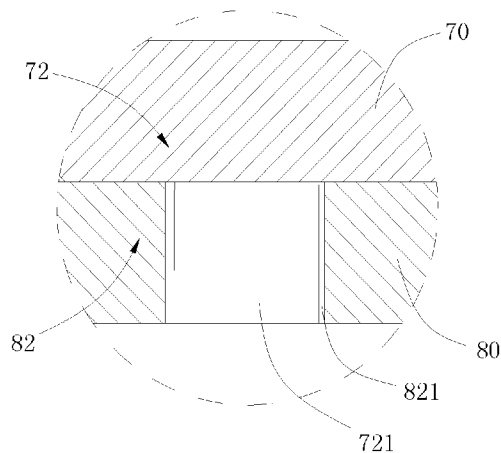


Fig. 12

(57) Abstract: A method for manufacturing an input assembly, an input assembly and a terminal are provided. The input assembly includes a reinforcing plate, a first flexible circuit board, a fingerprint chip package structure and a fixed plate. The reinforcing plate has a first positioning structure and configured to reinforce the first flexible circuit board and the fingerprint chip package structure. The first flexible circuit board is fixed on the reinforcing plate. The fingerprint chip package structure is fixed on the first flexible circuit board. The fixed plate is fixed to the terminal and has a second positioning structure. The first positioning structure is configured to be fitted with the second positioning structure, so as to limit a movement of the reinforcing plate relative to the fixed plate.



## METHOD FOR MANUFACTURING INPUT ASSEMBLY, INPUT ASSEMBLY AND TERMINAL

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### FIELD

The present disclosure relates to a field of terminals, and more particularly to an input assembly and a terminal.

### 10 BACKGROUND

In the related art, some mobile phones include a fingerprint chip package structure and a touch panel. When the fingerprint chip package structure is mounted into a through hole in the touch panel, the fingerprint chip package structure may have an unexpected movement, thereby affecting a mounting process of the fingerprint chip package structure.

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### SUMMARY

Embodiments of the present disclosure seek to solve at least one of the problems existing in the related art to at least some extent. To this end, an input assembly and a terminal are provided by the present disclosure.

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According to a first aspect of embodiments of the present disclosure, there is provided an input assembly. The input assembly includes a reinforcing plate, a first flexible circuit board, a fingerprint chip package structure and a fixed plate. The reinforcing plate has a first positioning structure and configured to reinforce the first flexible circuit board and the fingerprint chip package structure. The first flexible circuit board is fixed on the reinforcing plate. The fingerprint chip package structure is fixed on the first flexible circuit board. The fixed plate is fixed to the terminal and has a second positioning structure. The first positioning structure is configured to be fitted with the second positioning structure, so as to limit a movement of the reinforcing plate relative to the fixed plate.

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In the input assembly according to embodiments of the present disclosure, since the first positioning structure is fitted with the second positioning structure to limit the movement of the reinforcing plate relative to the fixed plate, a movement of the fingerprint chip package structure is

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limited, thus facilitating a mounting process of the fingerprint chip package structure.

In some embodiments, a plurality of first positioning structures are provided and a plurality of second positioning structures are provided, in which the number of the second positioning structures is corresponding to the number of the first positioning structures.

5 In some embodiments, the reinforcing plate includes a mounting portion and a connecting portion connected to the mounting portion, the first flexible circuit board is fixed on the mounting portion and the first positioning structure is provided at the connecting portion.

In some embodiments, one of the first positioning structure and the second positioning structure includes a protruding piece, and the other one of the first positioning structure and the  
10 second positioning structure has a fitting hole configured to be fitted with the protruding piece.

In some embodiments, the fingerprint chip package structure includes a package body and a fingerprint identification chip received in the package body, and the fingerprint identification chip is electrically connected with the first flexible circuit board.

In some embodiments, the package body includes a bottom surface and a lateral surface  
15 connected to the bottom surface, and defines a recessed portion at a junction of the bottom surface and the lateral surface.

In some embodiments, the package body includes a first package portion and a second package portion connected to the first package portion, the first package portion includes the bottom surface and the second package portion includes the lateral surface, the fingerprint  
20 identification chip is received in the first package portion.

In some embodiments, the input assembly includes a decoration enclosure, and the decoration enclosure includes: a decoration ring, in which the fingerprint chip package structure is accommodated in the decoration ring; and a supporting rim extending inwards from an inner wall of the decoration ring, in which the supporting rim is accommodated in the recessed portion and  
25 the fingerprint chip package structure is supported on the supporting rim.

According to a second aspect of embodiments of the present disclosure, there is provided a terminal, including a screen, a shell and an input assembly according to any one of above embodiments. The shell is configured to enclose the screen. The input assembly is received in the shell.

30 In the terminal according to embodiments of the present disclosure, since the first positioning structure is fitted with the second positioning structure to limit the movement of the reinforcing

plate relative to the fixed plate, the movement of the fingerprint chip package structure is limited, thus facilitating the mounting process of the fingerprint chip package structure.

In some embodiments, the input assembly includes a decoration enclosure coupled to the fingerprint chip package structure and configured to decorate the fingerprint chip package structure, in which the decoration enclosure includes: a decoration ring accommodating the  
5 fingerprint chip package structure therein; and a supporting rim extending inwards from an inner wall of the decoration ring and supporting the fingerprint chip package structure.

In some embodiments, the terminal further includes a touch panel located above the screen and defining a mounting hole to receive the decoration enclosure.

10 In some embodiments, the terminal further includes a second flexible circuit board coupled to the screen, in which a first orthographic projection of the decoration enclosure in the touch panel of the terminal overlaps a second orthographic projection of the second flexible circuit board in the touch panel of the terminal.

According to a third aspect of embodiments of the present disclosure, there is provided a  
15 method for manufacturing an input assembly of a terminal. The input assembly includes a fixed plate, a reinforcing plate, a first flexible circuit board, a decoration enclosure, a touch panel and a fingerprint chip package structure. The touch panel defines a through hole therein, and the method includes: mounting the decoration enclosure in the through hole of the touch panel from a first side  
20 of the touch panel; mounting the fingerprint chip package structure in the decoration enclosure from a second side of the touch panel, in which the second side of the touch panel is opposite to the first side of the touch panel; fixing the fixed plate to the terminal; mounting the reinforcing plate on the fixed plate and configuring a first positioning structure of the reinforcing plate to be fitted with a second positioning structure of the fixed plate, so as to limit a movement of the  
25 reinforcing plate relative to the fixed plate; fixing the first flexible circuit board on the reinforcing plate; and fixing the fingerprint chip package structure on the first flexible circuit board.

In the method for manufacturing the input assembly according to embodiments of the present disclosure, since the first positioning structure is fitted with the second positioning structure to limit the movement of the reinforcing plate relative to the fixed plate, the movement of the fingerprint chip package structure is limited, thus facilitating the mounting process of the  
30 fingerprint chip package structure.

In some embodiments, before mounting the fingerprint chip package structure in the

decoration enclosure from a second side of the touch panel, the method further includes: injecting a first adhesive between the decoration enclosure and an inner surface of a wall surrounding the through hole and adhering the first adhesive to the decoration enclosure and the inner surface of the wall surrounding the through hole; and solidifying the first adhesive so that the decoration enclosure is fixed in the through hole.

In some embodiments, the method further includes: injecting a second adhesive between the fingerprint chip package structure and the decoration enclosure and adhering the second adhesive to the fingerprint chip package structure and the decoration enclosure; and solidifying the second adhesive so that the fingerprint chip package structure is fixed in the decoration enclosure.

Additional aspects and advantages of embodiments of present disclosure will be given in part in the following descriptions, become apparent in part from the following descriptions, or be learned from the practice of the embodiments of the present disclosure.

## **BRIEF DESCRIPTION OF THE DRAWINGS**

These and/or other aspects and advantages of embodiments of the present disclosure will become apparent and more readily appreciated from the following descriptions made with reference to the drawings.

Fig. 1 is a plan view of a terminal according to embodiments of the present disclosure.

Fig. 2 is a partially sectional view of a terminal according to embodiments of the present disclosure.

Fig. 3 is an isometric view of a decoration enclosure according to embodiments of the present disclosure.

Fig. 4 is a sectional view of a decoration enclosure according to embodiments of the present disclosure.

Fig. 5 is a plan view of a decoration enclosure according to embodiments of the present disclosure.

Fig. 6 is an exploded perspective view of a decoration enclosure according to embodiments of the present disclosure.

Fig. 7 is another exploded perspective view of a decoration enclosure according to embodiments of the present disclosure.

Fig. 8 is a perspective view of a fingerprint chip package structure according to embodiments

of the present disclosure.

Fig. 9 is a sectional view of a fingerprint chip package structure according to embodiments of the present disclosure.

5 Fig. 10 is a plan view of a fingerprint chip package structure according to embodiments of the present disclosure.

Fig. 11 is a partially sectional view of the terminal shown in Fig. 2 along a direction of line XI-XI.

Fig. 12 is an enlarged view of part XII of the terminal shown in Fig. 11.

10 Fig. 13 is a flow chart of a method for manufacturing an input assembly of a terminal according to an embodiment of the present disclosure.

## DETAILED DESCRIPTION

Reference will be made in detail to embodiments of the present disclosure. The same or similar elements and the elements having same or similar functions are denoted by like reference numerals throughout the descriptions. The embodiments described herein with reference to 15 drawings are explanatory, illustrative, and used to generally understand the present disclosure. The embodiments shall not be construed to limit the present disclosure.

In the specification, it is to be understood that terms such as “central”, “longitudinal”, “lateral”, “length”, “width”, “thickness”, “upper”, “lower”, “front”, “rear”, “left”, “right”, 20 “vertical”, “horizontal”, “top”, “bottom”, “inner”, “outer”, “clockwise” and “counterclockwise” should be construed to refer to the orientation as then described or as shown in the drawings under discussion. These relative terms are for convenience of description and do not require that the present disclosure be constructed or operated in a particular orientation. In addition, terms such as “first” and “second” are used herein for purposes of description and are not intended to indicate or 25 imply relative importance or significance or to imply the number of indicated technical features. Thus, the feature defined with “first” and “second” may comprise one or more of this feature. In the description of the present disclosure, “a plurality of” means two or more than two, unless specified otherwise.

In the present disclosure, unless specified or limited otherwise, the terms “mounted”, 30 “connected”, “coupled”, “fixed” and the like are used broadly, and may be, for example, fixed connections, detachable connections, or integral connections; may also be mechanical or electrical

connections; may also be direct connections or indirect connections via intervening structures; may also be inner communications of two elements, which can be understood by those skilled in the art according to specific situations.

In the present disclosure, unless specified or limited otherwise, a structure in which a first feature is “on” or “below” a second feature may include an embodiment in which the first feature is in direct contact with the second feature, and may also include an embodiment in which the first feature and the second feature are not in direct contact with each other, but are contacted via an additional feature formed therebetween. Furthermore, a first feature “on”, “above” or “on top of” a second feature may include an embodiment in which the first feature is right or obliquely “on”, “above” or “on top of” the second feature, or just means that the first feature is at a height higher than that of the second feature; while a first feature “below”, “under” or “on bottom of” a second feature may include an embodiment in which the first feature is right or obliquely “below”, “under” or “on bottom of” the second feature, or just means that the first feature is at a height lower than that of the second feature.

Various embodiments and examples are provided in the following description to implement different structures of the present disclosure. In order to simplify the present disclosure, certain elements and settings will be described. However, these elements and settings are only by way of example and are not intended to limit the present disclosure. In addition, reference numerals may be repeated in different examples in the present disclosure. This repeating is for the purpose of simplification and clarity and does not refer to relations between different embodiments and/or settings. Furthermore, examples of different processes and materials are provided in the present disclosure. However, it would be appreciated by those skilled in the art that other processes and/or materials may be also applied.

Referring to Fig. 1 and Fig. 2, an input assembly 100 according to embodiments of the present disclosure includes a touch panel 10, a decoration enclosure 20 and a fingerprint chip package structure 30.

The input assembly 100 according to embodiments of the present disclosure can be applied to a terminal 1000, and the terminal 1000 can be configured as an electronic device such as a mobile phone or a tablet. It can be understood that, the terminal 1000 includes but is not limited to examples in the present embodiment. In some embodiments, the terminal 1000 further includes a screen 90 configured to display content and a shell 110 configured to enclose the screen 90.

In some embodiments, the touch panel 10 is received in the shell 110 and located above the screen 90. The touch panel 10 includes an upper surface 12 and a lower surface 14, as shown in Fig. 2. The upper surface 12 is opposite to the lower surface 14. It can be understood that, the upper surface 12 of the touch panel 10 is a facade of the input assembly 100, facing to a user. The user can make gesture operations (for example clicking or sliding) on the upper surface 12, so as to control the terminal 1000 to achieve corresponding functions.

The touch panel 10 can be made of light-transparent materials, such as glasses, ceramics or sapphires. As the touch panel 10 is configured as an input part of the terminal 1000, the touch panel 10 always suffers contacts, such as impacts or scratches. For example, when the user puts the terminal 1000 into his/her pocket, the touch panel 10 can be scratched and damaged by keys in the pocket of the user.

Therefore, the touch panel 10 can be made of materials having high hardness, for example the above-mentioned sapphires. Certainly, a protecting cover plate can be attached on the upper surface 12 of the touch panel 10, so as to prevent the touch panel 10 from being scratched.

Furthermore, the touch panel 10 includes a display region 15 intended for the user to view the content displayed in the screen 90 and a non-display region 16 for receiving the fingerprint chip package structure 30. In general, a middle region of the touch panel 10 is configured as the display region 15, and the non-display region 16 is arranged at a periphery of the display region 15. For example, the non-display region 16 is located at a top side or a bottom side of the display region 15.

As the touch panel 10 is made of the light-transparent materials, thus, the user can view content displayed in the screen 90 of the terminal 1000 through the display region 15.

For allowing the terminal 1000 to have a better appearance, ink can be sprayed on a lower surface 14 of the non-display region 16. The ink can have a color such as white, black or blue, and so on. A specific color can be set according to actual requirements. The ink can not only satisfy requirements of the user for terminals 1000 having various colors, but also shield structures inside the terminal 1000 so as to reach an effect of beautifying the terminal 1000.

In some embodiments, a shape of the touch panel 10 can be designed specifically according to a shape of the terminal 1000, for example being configured as a rounded rectangle.

Furthermore, the touch panel 10 has a mounting hole 17 therein. In the present embodiment, the mounting hole 17 is configured as a through hole running through the upper surface 12 and the



lower surface 14. In other embodiments, the mounting hole 17 can be configured a blind hole formed in the lower surface 14.

In the present embodiment, the mounting hole 17 is configured to have a long circle shape. Certainly, in other embodiments, the mounting hole 17 can have various shapes according to specific requirements, for example a round or oval shape. Therefore, examples of the shape of the mounting hole 17 in the present embodiment cannot be construed to limit the present disclosure.

In some embodiments, the decoration enclosure 20 is fitted in the mounting hole 17 and fixedly coupled to the touch panel 10. The fingerprint chip package structure 30 is accommodated in the decoration enclosure 20 and fixedly coupled to the decoration enclosure 20.

In general, a receiver of the terminal 1000 is disposed in a top region of the terminal 1000. Therefore, for preventing the mounting hole 17 from having an interference with the receiver, in some embodiments, the mounting hole 17 is provided in a bottom region of the touch panel 10, thereby providing a relatively large design space for the mounting hole 17. Furthermore, the mounting hole 17 is provided in the non-display region 16 of the touch panel 10.

In some embodiments, the mounting hole 17 is defined in the middle of the bottom region of the touch panel 10, so that the touch panel 10 presents an approximately symmetrical structure. Thus, the terminal 1000 has a better appearance and is easy to be operated by the user.

When the mounting hole 17 is configured as the through hole, during manufacture of the input assembly 100, the decoration enclosure 20 can be mounted into the mounting hole 17 from underneath of the touch panel 10 firstly, and then an adhesive is dispensed in a gap between an inner wall of the mounting hole 17 and the decoration enclosure 20, so that the decoration enclosure 20 is fixedly coupled to the touch panel 10.

Subsequently, the fingerprint chip package structure 30 is mounted into the decoration enclosure 20 from above of the touch panel 10, and the fingerprint chip package structure 30 is fixedly coupled to the decoration enclosure 20 through the adhesive.

When the mounting hole 17 is configured as the blind hole, the fingerprint chip package structure 30 can be mounted into the decoration enclosure 20 firstly, then the decoration enclosure 20 carried with the fingerprint chip package structure 30 can be mounted into the mounting hole 17, and the adhesive can be used to adhere and fix the decoration enclosure 20 to the touch panel 10.

Referring to Figs. 3-5, in some embodiments, the decoration enclosure 20 includes a

decoration ring 21 and a support rim 22. The support rim 22 extends inwards from an inner wall 211 of the decoration ring 21.

The support rim 22 of the decoration enclosure 20 according to embodiments of the present disclosure can support and position the fingerprint chip package structure 30, thereby improving an assembling efficiency of the fingerprint chip package structure 30 and the decoration enclosure 20.

That is to say, the fingerprint chip package structure 30 is supported on the support rim 22. When the fingerprint chip package structure 30 is mounted into the decoration ring 21, the fingerprint chip package structure 30 can be pressed from top to down. If the fingerprint chip package structure 30 cannot be moved any more, it indicates that the fingerprint chip package structure 30 abuts against the support rim 22 and is mounted to a preset location.

In some embodiments, the decoration ring 21 defines an accommodating hole 212, and the support rim 22 is located in the accommodating hole 212. The accommodating hole 212 can be configured to have a straight cylinder shape, or that is to say, the inner wall 211 is configured to be straight, so that the fingerprint chip package structure 30 is easy to be mounted in the accommodating hole 212 rapidly.

The accommodating hole 212 and the support rim 22 can be formed by removing materials from the parts through cutting process, or can be formed by casting.

For ensuring the strength of the decoration enclosure 20, in some embodiments, materials of the decoration enclosure 20 can be metal, for example stainless steel materials, thereby satisfying strength requirements of the decoration enclosure 20 as well as providing a corrosion resistance and improving a service life of the decoration enclosure 20. Certainly, the decoration enclosure 20 can also be made of other materials, such as plastics.

In some embodiments, furthermore, the fingerprint chip package structure 30 is accommodated in the decoration ring 21 and supported on the support rim 22.

In some embodiments, the support rim 22 is perpendicular to the inner wall 211 of the decoration ring 21.

Thus, the support rim 22 is easy to be formed, thereby reducing a production cost of the decoration ring 21. In addition, when the input assembly 100 is manufactured, the support rim 22 is located in a horizontal position, and the inner wall 211 of the decoration ring 21 is located in a vertical position, so that a surface of the fingerprint chip package structure 30 fitted with the

support rim 22 is a horizontal surface, thereby simplifying a structure of the fingerprint chip package structure 30 supported on the support rim 22.

In some embodiments, the decoration ring 21 includes a first bottom surface 213 connected to the inner wall 211, and a lower surface 221 of the support rim 22 is flush with the first bottom surface 213.

Among the decoration rings 21 having a same height, the decoration ring 21 having an arrangement described above has a relatively large accommodating space, so as to ensure that the fingerprint chip package structure 30 can be accommodated in the decoration ring 21.

Or, that is to say, in the case that the fingerprint chip package structure 30 has a constant thickness, a height of the decoration ring 21 is relatively small, thus reducing a height of the input assembly 100, thereby providing a design basis for reducing a thickness of the terminal 1000.

In some embodiments, the decoration ring 21 includes a top wall 214. The top wall 214 is connected to the inner wall 211. The top wall 214 includes a guiding surface 2142 facing towards an interior of the decoration enclosure 20.

In this way, the guiding surface 2142 can guide a finger of the user to enter the decoration ring 21 smoothly, so as to perform fingerprint identification operations, thereby improving an accuracy of the user performing the fingerprint identification operations. Furthermore, the guiding surface 2142 can be coated with a shiny metal layer (such as a chromium layer), so that the decoration ring 21 has a better appearance.

In some embodiments, the guiding surface 2142 can be configured as an annular surface, thereby facilitating the user to place the finger thereof in the decoration ring 21 from respective directions, so as to press the fingerprint chip package structure 30 and perform the fingerprint identification operations.

In some embodiments, the support rim 22 has a hole 222 therein.

Thus, the hole 222 contributes to a routing layout of a first flexible circuit board 40 coupled to the fingerprint chip package structure 30. For example, the first flexible circuit board 40 can run through the hole 222 so as to be coupled to the fingerprint chip package structure 30 (as shown in Fig. 2).

In some embodiments, the hole 222 is configured to have a rounded rectangle shape. A side wall 2221 surrounding the hole 222 has a groove 2222 along an axial direction (i.e. a left-right direction shown in Fig. 1) of the hole 222, and the groove 2222 is communicated with the hole

222.

For example, as shown in Fig. 2, after being coupled to the fingerprint chip package structure 30, the first flexible circuit board 40 firstly extends in a direction towards the groove 2222, then is bent and extends in an opposite direction running away from the groove 2222. Therefore, the groove 2222 can prevent the first flexible circuit board 40 from producing an interference with the side wall 2221, thereby facilitating wiring of the first flexible circuit board 40.

In some embodiments, the first flexible circuit board 40 is electrically coupled to the fingerprint chip package structure 30.

In some embodiments, the fingerprint chip package structure 30 is fixed on the first flexible circuit board 40. For example, the fingerprint chip package structure 30 is adhered and fixed to the first flexible circuit board 40 by adhesive.

In some embodiments, the decoration enclosure 20 includes a flange 23 extending outwards from an outer wall 215 of the decoration ring 21.

Thus, the flange 23 can abut against the lower surface 14 of the touch panel 10, thereby increasing a connecting area between the decoration enclosure 20 and the touch panel 10, and improving the reliability of fixedly connecting the decoration enclosure 20 with the touch panel 10.

In addition, when the decoration enclosure 20 is mounted into the mounting hole 17 from bottom to top, if the flange 23 abuts against the lower surface 14 of the touch panel 10, it indicates that the decoration enclosure 20 is mounted to a preset position. Therefore, the flange 23 is provided to improve the assembling efficiency of the input assembly 100 and to reduce the production cost of the input assembly 100.

In some embodiments, a sealing sheet can be provided between the flange 23 and the lower surface 14, so as to prevent water from entering the terminal 1000 through a gap between the decoration enclosure 20 and the mounting hole 17, thereby improving a water resistance effect of the terminal 1000.

In embodiments shown in Figs. 3-5, the flange 23 and the decoration ring 21 are integrally formed. However, in embodiments shown in Fig. 6 and Fig. 7, the flange 23 and the decoration ring 21 are separately formed. In some embodiments, the decoration ring 21 includes a muff-coupling portion 24, and the muff-coupling portion 24 is connected to the support rim 22. The flange 23 is fitted over the muff-coupling portion 24. Since the flange 23 and the decoration

ring 21 are separately formed, production difficulties of the decoration enclosure 20 can be reduced, so that uniformity of each decoration enclosure 20 can be improved when the decoration enclosure 20 is put into mass production.

In some embodiments, the muff-coupling portion 24 can have a through hole 24a through which the first flexible circuit board 40 can run.

In some embodiments, the muff-coupling portion 24 includes a connecting rim 241 and a bearing plate 242. The connecting rim 241 is connected to the support rim 22 and the bearing plate 242. The connecting rim 241 is substantially perpendicular to the support rim 22. The bearing plate 242 is substantially perpendicular to the connecting rim 241. The connecting rim 241 has the through hole 24a.

The muff-coupling portion 24 is hollow so as to accommodate a part or a whole of the fingerprint chip package structure 30. In some embodiments, the fingerprint chip package structure 30 can be supported on the bearing plate 242.

Referring to Figs. 3-5 again, in some embodiments, the flange 23 is perpendicular to the outer wall 215 of the decoration ring 21.

Thus, the manufacturing process of the decoration enclosure 20 is easy, and a contact area of the decoration enclosure 20 and the touch panel 10 can also be improved, in which the contact area is used for connection between the decoration enclosure 20 and the touch panel 10.

In some embodiments, the flange 23 includes a first protrusion 231 and a second protrusion 232 coupled to the first protrusion 231. The first protrusion 231 includes a first portion 2311 and a second portion 2312. The second portion 2312 is coupled to the first portion 2311 and the second protrusion 232. The second portion 2312 protrudes beyond the first portion 2311 and the second protrusion 232, that is, an outer edge of the second portion 2312 has a larger distance from the outer wall 215 of the decoration ring 21 than outer edges of the first portion 2311 and the second protrusion 232.

After the decoration enclosure 20 is mounted in the mounting hole 17, the first portion 2311 and the second protrusion 232 extend along a traverse direction of the touch panel 10 and the second portion 2312 extends along a longitudinal direction of the touch panel 10.

As the non-display region 16 has a relatively large arrangement space in the traverse direction, the second portion 2312 can protrude beyond the first portion 2311 and the second protrusion 232, so as to increase a connecting area of the flange 23 and the touch panel 10.

In addition, widths of the first portion 2311 and the second protrusion 232 are relatively small, thereby avoiding a longitudinal size of the non-display region 16 of the touch panel 10 from being increased due to the widths of the first portion 2311 and the second protrusion 232, such that an area ratio of the display region 15 to the touch panel 10 will not be reduced, and thus the appearance of the terminal 1000 will not be affected.

In some embodiments, a top surface 231a of the first protrusion 231 is flush with a top surface 232a of the second protrusion 232, and a thickness of the first portion 2311 is larger than a thickness of the second protrusion 232.

In some embodiments, when the decoration enclosure 20 is mounted in the mounting hole 17, the second protrusion 232 is closer to the display region 15, compared to the first portion 2311. Or, that is to say, the first portion 2311 is away from the display region 15, and the second protrusion 232 is close to the display region 15.

As there are more parts in a portion of the input assembly 100 close to the display region 15, the second protrusion 232 will not have an interference with other parts close to the display region 15 due to the small thickness of the second protrusion 232 (as shown in Fig. 2).

As shown in Fig. 2, the terminal 1000 further includes a second flexible circuit board 50 coupled to the screen 90 of the terminal 1000. An orthographic projection of the decoration enclosure 20 in the lower surface 14 of the touch panel 10 overlaps orthographic projections of the second flexible circuit board 50 and of other parts in the lower surface 14 of the touch panel 10, as indicated by a region limited between two dotted lines in Fig. 2, while the second protrusion 232 will not have an interference with the second flexible circuit board 50 and the other parts due to the small thickness of the second protrusion 232, so that the decoration enclosure 20 can be closer to the display region 15 and even can be partially or entirely in the display region 15 of the touch panel 10, thus reducing an area ratio of the non-display region 16 to the touch panel 10 and improving the area ratio of the display region 15 to the touch panel 10.

In some embodiments, the orthographic projection of the decoration enclosure 20 in the lower surface 14 of the touch panel 10 may completely overlap the orthographic projection of the second flexible circuit board 50 in the lower surface 14 of the touch panel 10, but the present disclosure is not limited to this. For example, in other embodiments, the orthographic projection of the decoration enclosure 20 in the lower surface 14 of the touch panel 10 may partially overlap the orthographic projection of the second flexible circuit board 50 in the lower surface 14 of the touch

panel 10.

In some embodiments, the decoration ring 21 is configured to have a long circle shape. The outer wall 215 of the decoration ring 21 includes two straight segments 2151 in parallel and two curved segments 2152 each connected to the two straight segments 2151. The first portion 2311 is provided to one of the two straight segments 2151, and the second portion 2312 is provided to each curved segment 2152. As shown in Fig. 5, two second portions 2312 are provided, and the two second portions 2312 are provided to the two curved segments 2152 respectively.

Thus, the decoration ring 21 has the better appearance. In some embodiments, the two curved segments 2152 are arrayed in two lines along the traverse direction (for example the left-right direction shown in Fig. 1) of the touch panel 10, and the two straight segments 2151 are arrayed in two lines along the longitudinal direction (perpendicular to the traverse direction) of the touch panel 10.

In some embodiments, a shape of the second portion 2312 is matched with a shape of the curved segment 2152.

For example, an outer contour of the second portion 2312 also has an arc shape, and the second portion 2312 and the curved segment 2152 are substantially concentrically arranged, so that the decoration enclosure 20 has a more compact structure.

Referring to Fig. 8-Fig. 10, in some embodiments, the fingerprint chip package structure 30 includes a package body 31 and a fingerprint identification chip 32.

The package body 31 includes a second bottom surface 311 and a lateral surface 312 connected to the second bottom surface 311, and a recessed portion 33 is formed at a junction of the second bottom surface 311 and the lateral surface 312. The fingerprint identification chip 32 is received in the package body 31.

In the fingerprint chip package structure 30 according to embodiments of the present disclosure, the recessed portion 33 can be fitted with the support rim 22 of the decoration enclosure 20, thereby positioning the fingerprint chip package structure 30, and further improving the assembling efficiency of the fingerprint chip package structure 30.

In addition, since the recessed portion 33 is fitted with the support rim 22, a thickness of the fingerprint chip package structure 30 can be reduced, thus facilitating miniaturization of the terminal 1000 to which the fingerprint chip package structure 30 is applied.

In some embodiments, when the user performs an operation to unlock the terminal 1000 via a

fingerprint, the finger can be put in a position corresponding to the fingerprint identification chip 32. A signal of the fingerprint identification chip 32 is transmitted through the package body 31 so as to collect and identify a fingerprint pattern of the user, and then the fingerprint pattern of the user is matched with a prestored fingerprint pattern. If the matching is successful, the terminal 5 1000 is unlocked.

In some embodiments, a surface of the fingerprint identification chip 32 facing towards the finger of the user is provided with a sensing pixel array, so as to collect the fingerprint pattern of the user. The package body 31 packages the fingerprint identification chip 32, so as to reduce influences of other interference signals on the sensing pixel array when the sensing pixel array 10 collects the fingerprint pattern, thus improving an accuracy of the identification.

In some embodiments, the recessed portion 33 is configured to be fitted with the support rim 22, that is to say, the support rim 22 is configured to be accommodated in the recessed portion 33, so that the fingerprint chip package structure 30 is supported on the support rim 22 through the recessed portion 33.

15 In the present embodiment, the recessed portion 33 is configured to be annular. Correspondingly, the support rim 22 also is configured to be annular, so that the recessed portion 33 can accommodate the support rim 22.

In other embodiments, a plurality of recessed portions 33 spaced apart from one another along a circumferential direction of the junction of the second bottom surface 311 and the lateral surface 20 312 can be provided, and correspondingly, a plurality of support rims 22 spaced apart from one another along the circumferential direction can be also provided. The plurality of recessed portions 33 are fitted with the plurality of support rims 22 correspondingly.

For example, three recessed portions 33 can be provided, and two adjacent recessed portions 33 are spaced apart from each other by  $120^\circ$  along the circumferential direction. Three support 25 rims 22 can also be provided, and the three support rims 22 are corresponding to the three recessed portions 33 with respect to the structural position.

In some embodiments, the shape and the number of the recessed portion 33 are not limited to the above-discussed cases, as long as the recessed portion 33 is fitted with the support rim 22, so that the support rim 22 can support the fingerprint chip package structure 30. Therefore, the 30 above-mentioned examples cannot be construed to limit the present disclosure.

Certainly, in some embodiments, when the thickness of the fingerprint chip package structure



30 is relatively small, the recessed portion 33 can be omitted from the fingerprint chip package structure 30.

In some embodiments, the package body 31 includes a first package portion 313 and a second package portion 314 coupled to the first package portion 313. The first package portion 313 includes the second bottom surface 311, and the second package portion 314 includes the lateral surface 312.

Thus, the recessed portion 33 can be defined by the first package portion 313 and the second package portion 314. For example, the package body 31 can be provided with the recessed portion 33 by cutting off materials from the package body 31, i.e. via the cutting process, or the recessed portion 33 can also be directly formed together with the package body 31 by casting.

In some embodiments, for forming the recessed portion 33, a cross-section area of the first package portion 313 is smaller than a cross-section area of the second package portion 314.

In some embodiments, the first package portion 313 is received in the hole 222, and the second package portion 314 is supported on the support rim 22.

In some embodiments, the fingerprint identification chip 32 is received in the first package portion 313.

Thus, a circuit junction of the fingerprint identification chip 32 is easy to be exposed, so as to be coupled to the first flexible circuit board 40.

In some embodiments, a shape and a size of the first package portion 313 are matched with a shape and a size of the fingerprint identification chip 32.

Or, that is to say, the shape of the fingerprint identification chip 32 is similar to or same with the shape of the first package portion 313. For example, the fingerprint identification chip 32 is configured to have a cuboid shape and the first package portion 313 is configured to have a cuboid or a rounded cuboid shape.

The size of the first package portion 313 is slightly larger than the size of the fingerprint identification chip 32, so as to achieve an effect of packaging the fingerprint identification chip 32. Thus, the fingerprint chip package structure 30 has the more compact structure.

In some embodiments, the first package portion 313 has the rounded cuboid shape.

Thus, the package body 31 can be better fitted with the fingerprint identification chip 32. Furthermore, the shape of the first package portion 313 is matched with a shape of the hole 222, that is to say, the hole 222 also has the rounded cuboid shape.

In some embodiments, the second package portion 314 includes a top surface 3141 connected to the lateral surface 312. The fingerprint chip package structure 30 includes a cover plate 34 fixed on the top surface 3141 of the second package portion 314. For example, the cover plate 34 can be fixed on the top surface 3141 of the second package portion 314 through adhesive.

5 When the user performs the fingerprint identification operation, the finger can press on the cover plate 34. The cover plate 34 can protect the package body 31 from being damaged, so as to improve the reliability of the fingerprint chip package structure 30.

As the cover plate 34 suffers touches frequently, the cover plate 34 can be made of materials having high hardness, for example the sapphires materials mentioned above.

10 In some embodiments, a shape and a size of the cover plate 34 are matched with a shape and a size of the top surface 3141 of the second package portion 314.

For example, the top surface 3141 is configured to have a long circle shape, and the cover plate 34 is also configured to have a long circle shape. An area of the cover plate 34 is slightly larger than an area of the top surface 3141 of the second package portion 314. Thus, the cover  
15 plate 34 can cover the second package portion 314 entirely.

In some embodiments, a sealing member 60 is provided between the second package portion 314 and the support rim 22. The sealing member 60 is configured to seal a gap between the second package portion 314 and the support rim 22. For example, the sealing member 60 is made of silica gel (as shown in Fig. 2).

20 Thus, the sealing member 60 can prevent foreign matters (such as water and dust) from entering the terminal 1000 from a gap between the fingerprint chip package structure 30 and the decoration enclosure 20, thereby improving the waterproof and dustproof effects of the terminal 1000.

In some embodiments, the recessed portion 33 includes a first surface 331 and a second  
25 surface 332 connected to the first surface 331, and the first surface 331 is perpendicular to the second surface 332.

Thus, the recessed portion 33 is easy to be formed, and the first surface 331 is easy to be connected to the support rim 22. The first surface 331 is perpendicular to the second surface 332, so that the package body 31 is configured to have a stepped shape.

30 In some embodiments, the sealing member 60 is between the first surface 331 and the support rim 22.

In some embodiments, a junction of the first surface 331 and the second surface 332 is configured to be a transition fillet.

Thus, defects (such as cracks) are not easy to occur at the junction of the first surface 331 and the second surface 332 and the recessed portion 33 is easy to be formed.

5 Referring to Fig. 2, Fig. 11 and Fig. 12, in some embodiments, the input assembly 100 includes a reinforcing plate 70 and a fixed plate 80. The reinforcing plate 70 is provided with a first positioning structure 72. The first flexible circuit board 40 is fixed on the reinforcing plate 70. The fixed plate 80 is provided with a second positioning structure 82, and the first positioning structure 72 is configured to be fitted with the second positioning structure 82, so as to limit a  
10 movement of the reinforcing plate 70 relative to the fixed plate 80.

Therefore, since the first positioning structure 72 is fitted with the second positioning structure 82 to limit the movement of the reinforcing plate 70 relative to the fixed plate 80, a movement of the fingerprint chip package structure 30 is limited, thus facilitating a mounting process of the fingerprint chip package structure 30.

15 For example, when the movement of the fingerprint chip package structure 30 is limited, the adhesive can be dispensed into the gap between the fingerprint chip package structure 30 and the decoration enclosure 20, so as to fix and adhere the fingerprint chip package structure 30 to the decoration enclosure 20, so that a position of the fingerprint chip package structure 30 is fixed.

In some embodiments, the fingerprint chip package structure 30 and the reinforcing plate 70  
20 are located on two opposite surfaces of the first flexible circuit board 40 respectively. The fixed plate 80 is arranged below the reinforcing plate 70. The reinforcing plate 70 is further configured to reinforce the first flexible circuit board 40 and the fingerprint chip package structure 30. When the input assembly 100 is assembled, the fixed plate 80 can be fixed to the terminal 1000 firstly, and then the reinforcing plate 70 carried with the fingerprint chip package structure 30 can be  
25 mounted to the fixed plate 80 through a fit of the first positioning structure 72 and the second positioning structure 82.

For ensuring a strength of the reinforcing plate 70, the reinforcing plate 70 can be made of metal materials, for example stainless steel.

In some embodiments, a plurality of first positioning structures 72 can be provided, and a  
30 plurality of second positioning structures 82 can also be provided. The number of the second positioning structures 82 is corresponding to the number of the first positioning structures 72.

Thus, the plurality of first positioning structures 72 are fitted with the plurality of second positioning structures 82 respectively, so as to further limit the movement of the reinforcing plate 70, thus limiting the movement of the fingerprint chip package structure 30.

In some embodiments, the reinforcing plate 70 includes a mounting portion 74 for mounting the first flexible circuit board 40 and a connecting portion 76 connected to the mounting portion 74. The first flexible circuit board 40 is fixed on the mounting portion 74, and the first positioning structure 72 is provided at the connecting portion 76.

Thus, the connecting portion 76 can extend beyond the first flexible circuit board 40, so as to prevent the first positioning structure 72 provided at the connecting portion 76 from having an interference with the first flexible circuit board 40. In some embodiments, the mounting portion 74 is integrally formed with the connecting portion 76.

In some embodiments, two connecting portions 76 are provided, and the two connecting portions 76 are connected to two opposite ends of the mounting portion 74 respectively. Each connecting portion 76 is provided with the first positioning structure 72.

Since the first positioning structure 72 is provided at each of the connecting portions 76 connected to the two opposite ends of the mounting portion 74, the reinforcing plate 70 is subjected to a more uniform force, when the first positioning structure 72 is fitted with the second positioning structure 82, thus improving the connection reliability of the reinforcing plate 70 and the fixed plate 80.

In some embodiments, the first positioning structure 72 includes a protruding piece 721, and the second positioning structure 82 has a fitting hole 821 configured to be fitted with the protruding piece 721. The protruding piece 721 is configured to be accommodated in the fitting hole 821.

Thus, configurations of the first positioning structure 72 and the second positioning structure 82 are simple, so that the reinforcing plate 70 and the fixed plate 80 are easy to be manufactured, thereby reducing the production cost of the input assembly 100.

In some embodiments, in the example shown in Fig. 12, the fitting hole 821 is configured as a through hole. However in other embodiments, the fitting hole 821 can be configured as a blind hole.

In some embodiments, in other embodiments, the first positioning structure 72 can have the fitting hole, and the second positioning structure 82 can include the protruding piece configured to

be fitted with the fitting hole. The protruding piece is also configured to be accommodated in the fitting hole.

Furthermore, embodiments of the present disclosure also provide a method for manufacturing an input assembly of a terminal. The input assembly includes a fixed plate 80, a reinforcing plate 70, a first flexible circuit board 40, a decoration enclosure 20, a touch panel 10 and a fingerprint chip package structure 30. The touch panel 10 has a through hole 17 therein. As shown in Fig. 13, the method includes actions at following blocks.

At block 1301, the decoration enclosure 20 is mounted in the through hole 17 of the touch panel 10 from a first side of the touch panel 10, for example from a lower side of the touch panel 10.

At block 1302, the fingerprint chip package structure 30 is mounted in the decoration enclosure 20 from a second side of the touch panel 10. The second side of the touch panel 10 is opposite to the first side of the touch panel 10. For example, the second side of the touch panel 10 is an upper side of the touch panel 10.

At block 1303, the fixed plate 80 is fixed to the terminal.

At block 1304, the reinforcing plate 70 is mounted on the fixed plate 80 and a first positioning structure of the reinforcing plate 70 is configured to be fitted with a second positioning structure of the fixed plate 80, so as to limit a movement of the reinforcing plate 70 relative to the fixed plate 80.

At block 1305, the first flexible circuit board 40 is fixed on the reinforcing plate 70.

At block 1306, the fingerprint chip package structure 30 is fixed on the first flexible circuit board 40.

In some embodiments of the present disclosure, before the action that the fingerprint chip package structure 30 is mounted in the decoration enclosure 20, the method includes followings:

a first adhesive is injected between the decoration enclosure 20 and an inner surface of a wall surrounding the through hole 17 and the first adhesive is adhered to the decoration enclosure 20 and the inner surface of the wall surrounding the through hole 17; and

the first adhesive is solidified so that the decoration enclosure 20 is fixed in the through hole 17.

In some embodiments of the present disclosure, after the action that the fingerprint chip package structure 30 is fixed on the first flexible circuit board 40, the method further includes

followings:

a second adhesive is injected between the fingerprint chip package structure 30 and the decoration enclosure 20 and the second adhesive is adhered to the fingerprint chip package structure 30 and the decoration enclosure 20; and

5 the second adhesive is solidified so that the fingerprint chip package structure 30 is fixed in the decoration enclosure 20.

With the method for manufacturing the input assembly, since the movement of the fingerprint chip package structure 30 is limited relative to the fixed plate 80, it is convenient to fix the fingerprint chip package structure 30 in the decoration enclosure 20, thus contributing to  
10 assembling of the input assembly.

Reference throughout this specification to “an embodiment”, “some embodiments”, “one embodiment”, “another example”, “an example”, “a specific example” or “some examples” means that a particular feature, structure, material, or characteristic described in connection with the embodiment or example is included in at least one embodiment or example of the present  
15 disclosure. Thus, the appearances of the phrases such as “in some embodiments”, “in one embodiment”, “in an embodiment”, “in another example”, “in an example”, “in a specific example” or “in some examples” in various places throughout this specification are not necessarily referring to the same embodiment or example of the present disclosure. Furthermore, the particular features, structures, materials, or characteristics may be combined in any suitable manner in one or  
20 more embodiments or examples.

Although explanatory embodiments have been shown and described, it would be appreciated by those skilled in the art that the above embodiments cannot be construed to limit the present disclosure, and changes, alternatives, and modifications can be made in the embodiments without departing from spirit, principles and scope of the present disclosure.

25

## CLAIMS

1. An input assembly (100) for a terminal, comprising:  
a reinforcing plate (70) having a first positioning structure (72);  
5 a first flexible circuit board (40) fixed on the reinforcing plate (70);  
a fingerprint chip package structure (30) fixed on the first flexible circuit board (40); and  
a fixed plate (80) fixed to the terminal and having a second positioning structure (82),  
wherein the reinforcing plate (70) is configured to reinforce the first flexible circuit board (40)  
and the fingerprint chip package structure (30), and the first positioning structure (72) is  
10 configured to be fitted with the second positioning structure (82), so as to limit a movement of the  
reinforcing plate (70) relative to the fixed plate (80).
2. The input assembly (100) according to claim 1, wherein a plurality of first positioning  
structures (72) are provided and a plurality of second positioning structures (82) are provided,  
wherein the number of the second positioning structures (82) is corresponding to the number  
15 of the first positioning structures (72).
3. The input assembly (100) according to claim 1 or 2, wherein the reinforcing plate (70)  
comprises a mounting portion (74) and a connecting portion (76) connected to the mounting  
portion (74), the first flexible circuit board (40) is fixed on the mounting portion (74) and the first  
positioning structure (72) is provided at the connecting portion (76).
- 20 4. The input assembly (100) according to any one of claims 1-3, wherein one of the first  
positioning structure (72) and the second positioning structure (82) comprises a protruding piece,  
and the other one of the first positioning structure (72) and the second positioning structure (82)  
has a fitting hole configured to be fitted with the protruding piece.
5. The input assembly (100) according to any one of claims 1-4, wherein the fingerprint chip  
25 package structure (30) comprises a package body (31) and a fingerprint identification chip (32)  
received in the package body (31), and the fingerprint identification chip (32) is electrically  
connected with the first flexible circuit board (40).
6. The input assembly (100) according to claim 5, wherein the package body (31) comprises a  
bottom surface (311) and a lateral surface (312) connected to the bottom surface (311), and defines  
30 a recessed portion (33) at a junction of the bottom surface (311) and the lateral surface (312).
7. The input assembly (100) according to claim 6, wherein the package body (31) comprises a

first package portion (313) and a second package portion (314) connected to the first package portion (313),

the first package portion (313) comprises the bottom surface (311) and the second package portion (314) comprises the lateral surface (312),

5 the fingerprint identification chip (32) is received in the first package portion (313).

8. The input assembly (100) according to claim 6 or 7, wherein the input assembly (100) comprises a decoration enclosure (20), and the decoration enclosure (20) comprises:

a decoration ring (21), wherein the fingerprint chip package structure (30) is accommodated in the decoration ring (21); and

10 a supporting rim (22) extending inwards from an inner wall (211) of the decoration ring (21), wherein the supporting rim (22) is accommodated in the recessed portion (33) and the fingerprint chip package structure (30) is supported on the supporting rim (22).

9. A terminal (1000), comprising:

a screen (90);

15 a shell (110) configured to enclose the screen (90); and

an input assembly (100) according to any one of claims 1-8 and received in the shell (110).

10. The terminal (1000) according to claim 9, wherein the input assembly (100) comprises a decoration enclosure (20) coupled to the fingerprint chip package structure (30) and configured to decorate the fingerprint chip package structure (30), wherein the decoration enclosure (20) comprises:

a decoration ring (21) accommodating the fingerprint chip package structure (30) therein; and

a supporting rim (22) extending inwards from an inner wall (211) of the decoration ring (21) and supporting the fingerprint chip package structure (30).

11. The terminal (1000) according to claim 10, further comprising a touch panel (10) located 25 above the screen (90) and defining a mounting hole (17) to receive the decoration enclosure (20).

12. The terminal (1000) according to claim 11, further comprising a second flexible circuit board (50) coupled to the screen (90), wherein a first orthographic projection of the decoration enclosure (20) in the touch panel (10) of the terminal (1000) overlaps a second orthographic projection of the second flexible circuit board (50) in the touch panel (10) of the terminal (1000).

30 13. A method for manufacturing an input assembly of a terminal, the input assembly comprising a fixed plate, a reinforcing plate, a first flexible circuit board, a decoration enclosure, a



touch panel and a fingerprint chip package structure, the touch panel defining a through hole therein, and the method comprising:

mounting the decoration enclosure in the through hole of the touch panel from a first side of the touch panel;

5 mounting the fingerprint chip package structure in the decoration enclosure from a second side of the touch panel, in which the second side of the touch panel is opposite to the first side of the touch panel;

fixing the fixed plate to the terminal;

10 mounting the reinforcing plate on the fixed plate and configuring a first positioning structure of the reinforcing plate to be fitted with a second positioning structure of the fixed plate, so as to limit a movement of the reinforcing plate relative to the fixed plate;

fixing the first flexible circuit board on the reinforcing plate; and

fixing the fingerprint chip package structure on the first flexible circuit board.

14. The method according to claim 13, before mounting the fingerprint chip package structure  
15 in the decoration enclosure from a second side of the touch panel, further comprising:

injecting a first adhesive between the decoration enclosure and an inner surface of a wall surrounding the through hole and adhering the first adhesive to the decoration enclosure and the inner surface of the wall surrounding the through hole; and

solidifying the first adhesive so that the decoration enclosure is fixed in the through hole.

20 15. The method according to claim 13 or 14, further comprising:

injecting a second adhesive between the fingerprint chip package structure and the decoration enclosure and adhering the second adhesive to the fingerprint chip package structure and the decoration enclosure; and

25 solidifying the second adhesive so that the fingerprint chip package structure is fixed in the decoration enclosure.

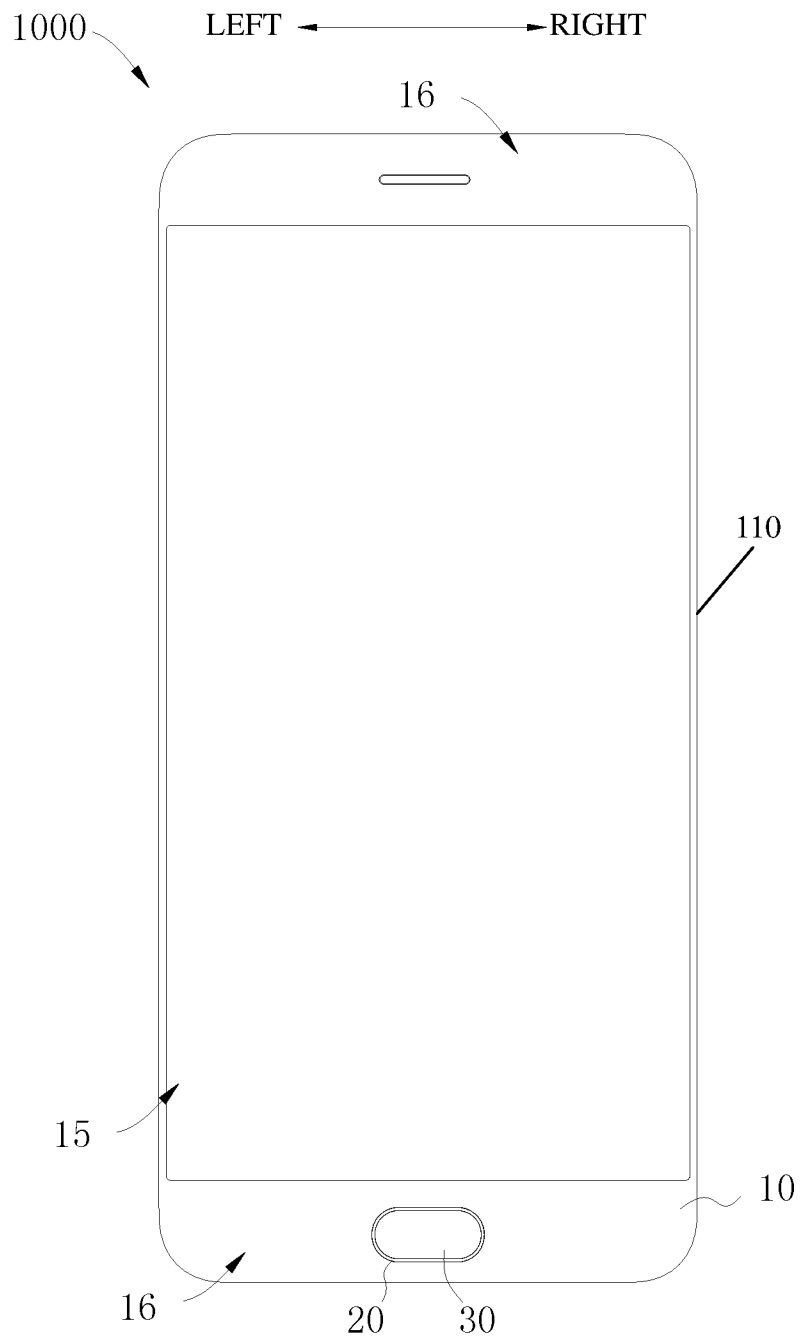


Fig. 1

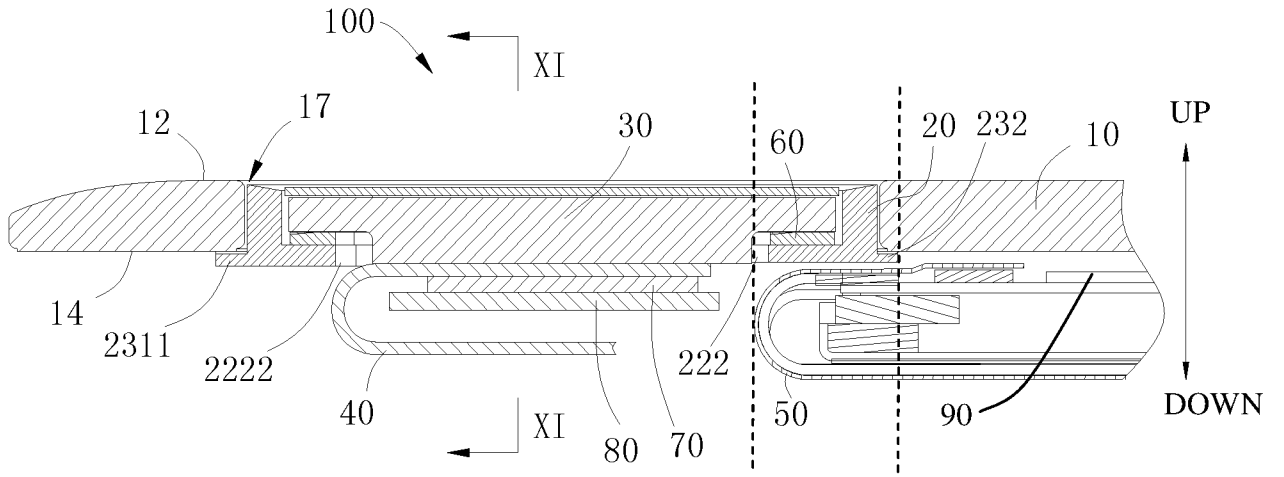


Fig. 2

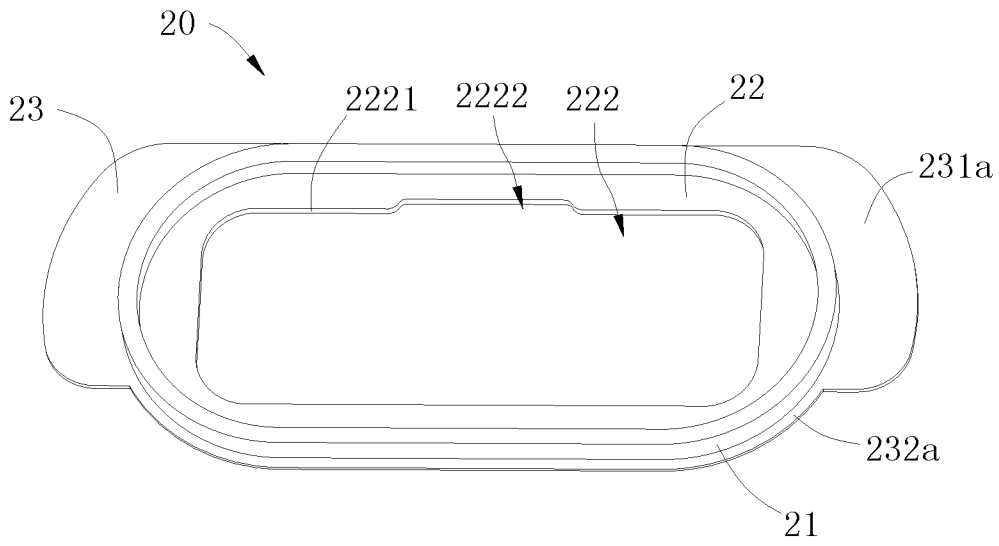


Fig. 3

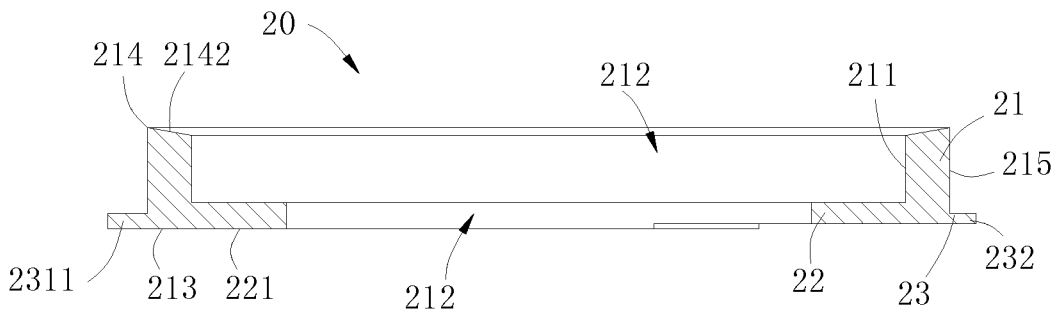


Fig. 4

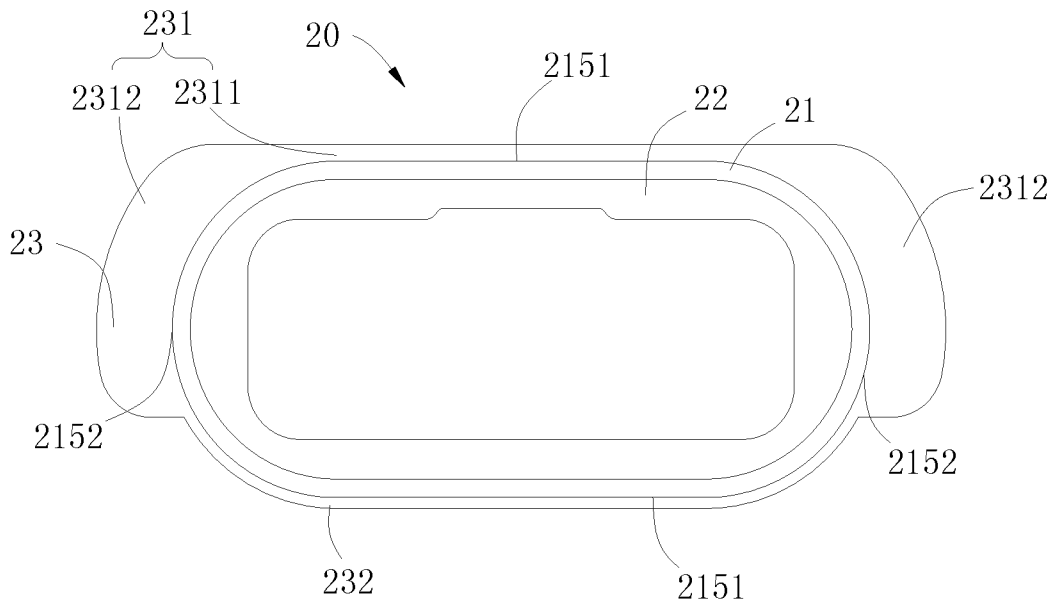


Fig. 5

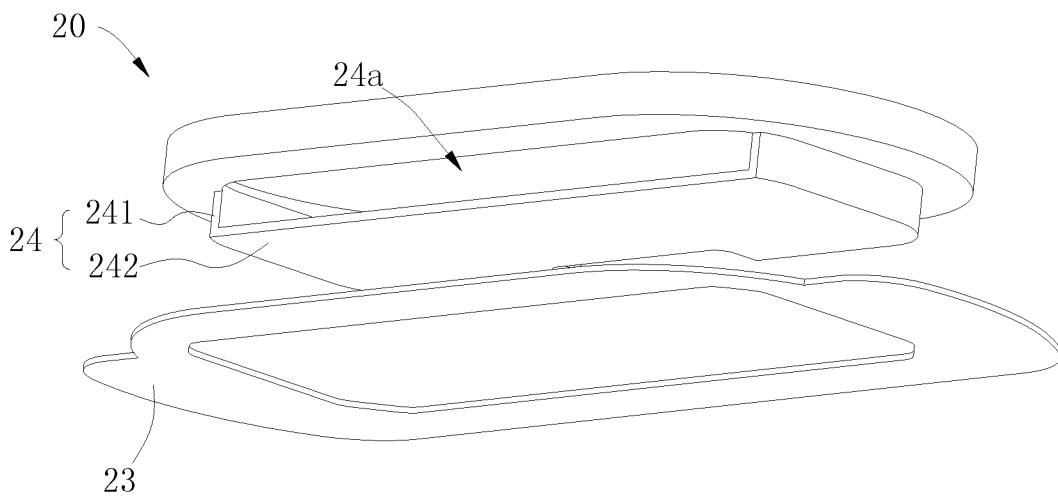


Fig. 6

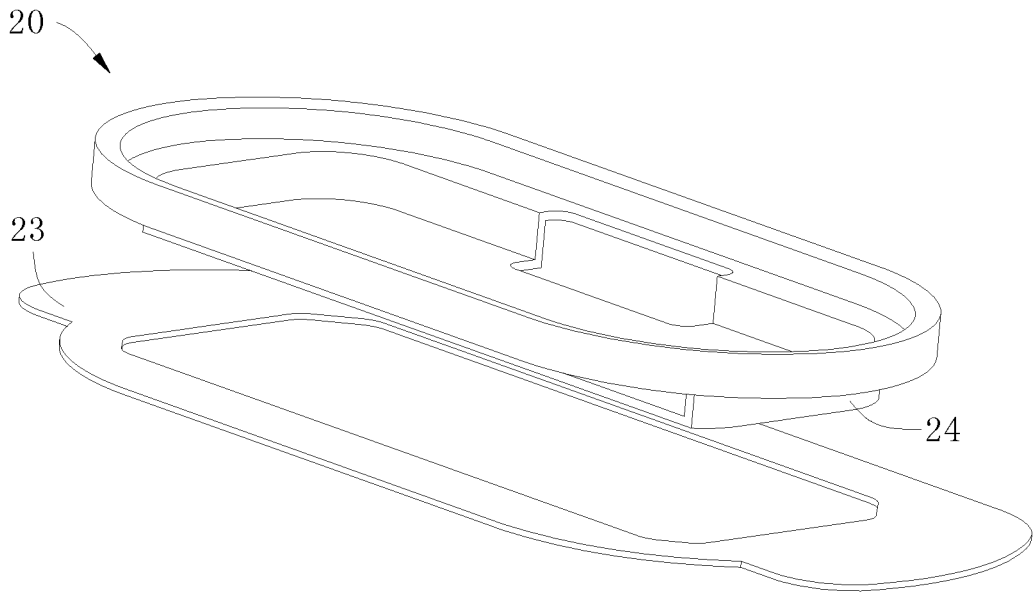


Fig. 7

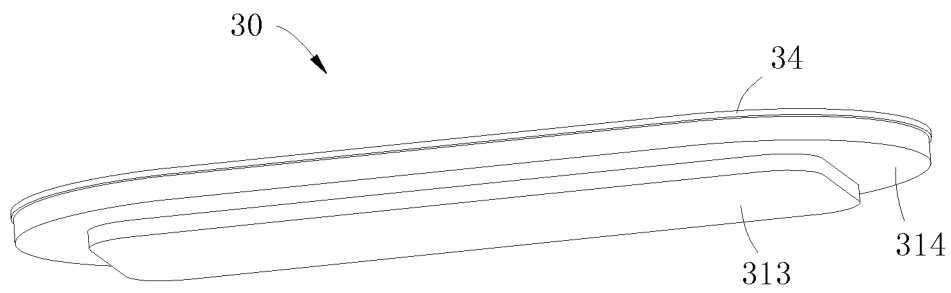


Fig. 8

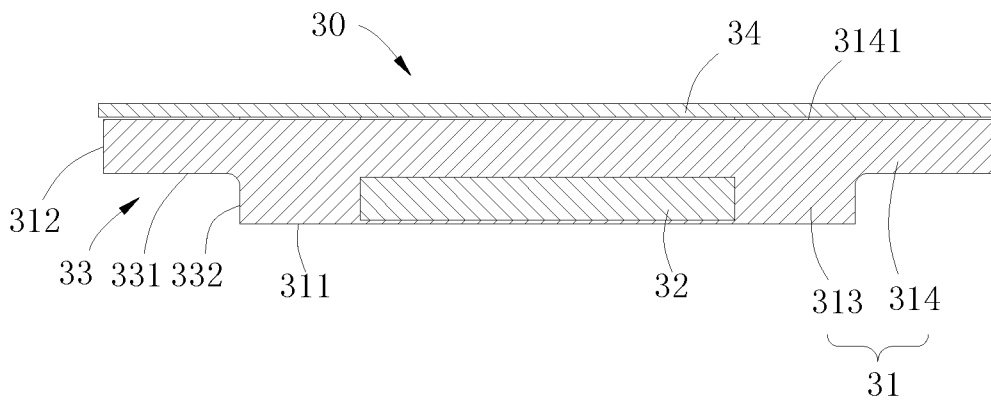


Fig. 9

30

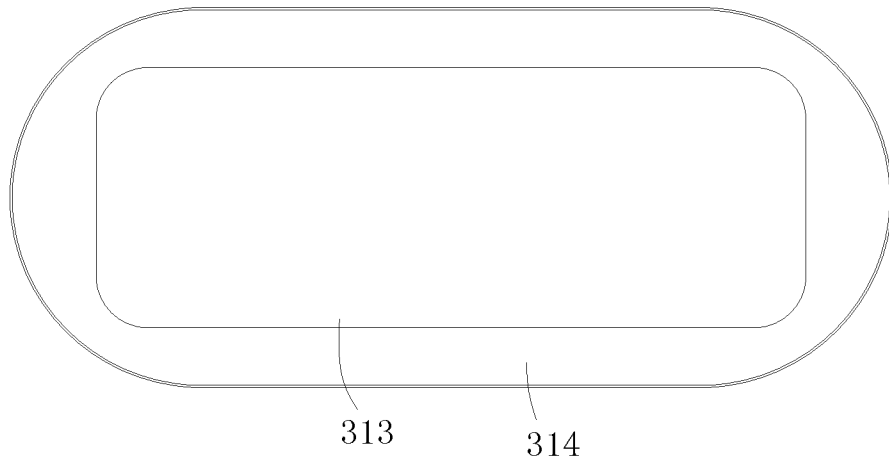


Fig. 10

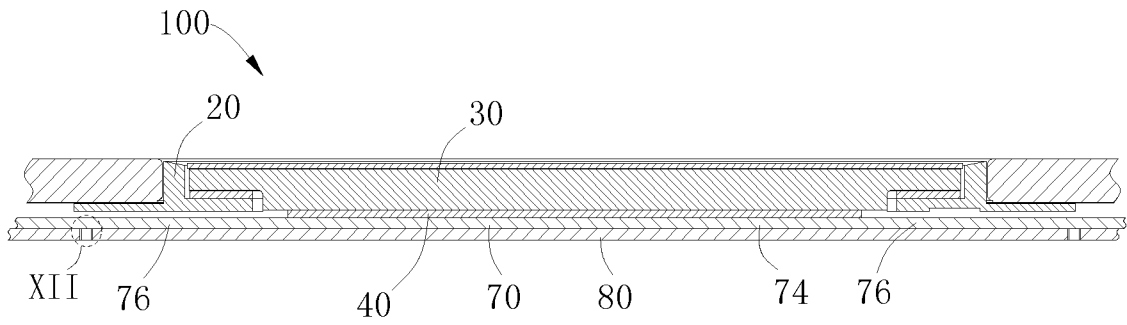


Fig. 11

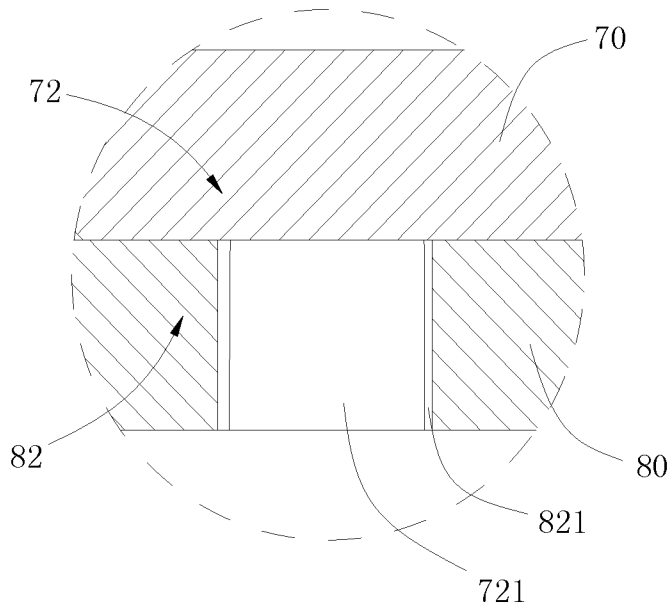


Fig. 12

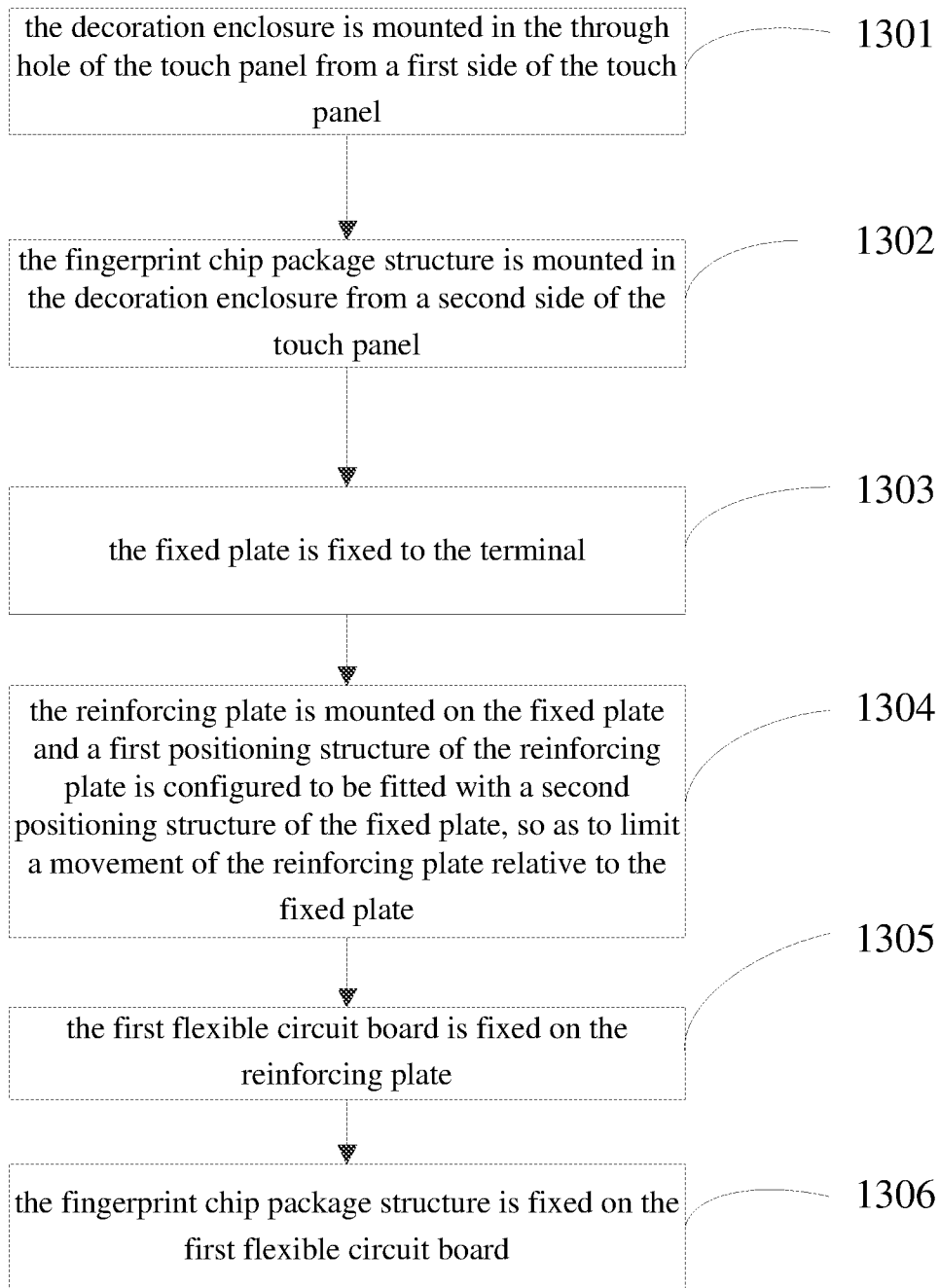


Fig. 13

## INTERNATIONAL SEARCH REPORT

International application No.

PCT/CN2017/090336

**A. CLASSIFICATION OF SUBJECT MATTER**

G06F 3/041(2006.01)i

According to International Patent Classification (IPC) or to both national classification and IPC

**B. FIELDS SEARCHED**

Minimum documentation searched (classification system followed by classification symbols)

G06F

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

CNPAT, CNKI, WPI, EPODOC, GOOGLE: terminal, fingerprint identification, chip, IC, package structure, flexible circuit board, PCB, reinforcing plate, fixed plate, fix, assemble, protruding, hole, flute, position, decoration ring, shell, adhesive

**C. DOCUMENTS CONSIDERED TO BE RELEVANT**

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
PX	CN 206133504 U (GUANGDONG OPPO MOBILE TELECOMMUNICATIONS CO., LTD.) 26 April 2017 (2017-04-26) see description, paragraphs [0039]-[0149] and figures 1-12	1-15
PX	CN 106095196 A (GUANGDONG OPPO MOBILE TELECOMMUNICATIONS CO., LTD.) 09 November 2016 (2016-11-09) see description, paragraphs [0039]-[0149] and figures 1-12	1-15
Y	CN 105825165 A (VIVO MOBILE COMMUNICATION CO., LTD.) 03 August 2016 (2016-08-03) see description, paragraphs [0031]-[0045], [0052]-[0085] and figure 3	1-15
Y	CN 205080566 U (SHENZHEN OUFEI INVESTMENT HOLDING CO., LTD.) 09 March 2016 (2016-03-09) see description, paragraphs [0002], [0024]-[0037] and figures 1-6	1-15
Y	CN 105205474 A (SHENZHEN OUFEI INVESTMENT HOLDING CO., LTD.) 30 December 2015 (2015-12-30) see description, paragraphs [0002], [0024]-[0037] and figures 1-6	1-15
A	CN 204833297 U (BYD CO., LTD.) 02 December 2015 (2015-12-02) the whole document	1-15

 Further documents are listed in the continuation of Box C. See patent family annex.

\* Special categories of cited documents:

“A” document defining the general state of the art which is not considered to be of particular relevance

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“P” document published prior to the international filing date but later than the priority date claimed

“T” later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention

“X” document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

“Y” document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

“&” document member of the same patent family

Date of the actual completion of the international search

12 September 2017

Date of mailing of the international search report

28 September 2017

Name and mailing address of the ISA/CN

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**INTERNATIONAL SEARCH REPORT**  
**Information on patent family members**

International application No.

**PCT/CN2017/090336**

Patent document cited in search report			Publication date (day/month/year)	Patent family member(s)	Publication date (day/month/year)
CN	206133504	U	26 April 2017	None	
CN	106095196	A	09 November 2016	None	
CN	105825165	A	03 August 2016	None	
CN	205080566	U	09 March 2016	None	
CN	105205474	A	30 December 2015	None	
CN	204833297	U	02 December 2015	None	